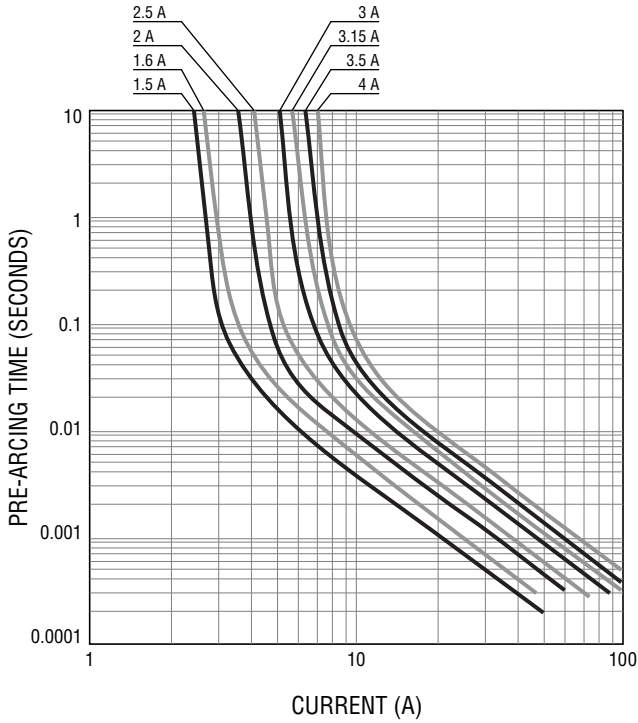
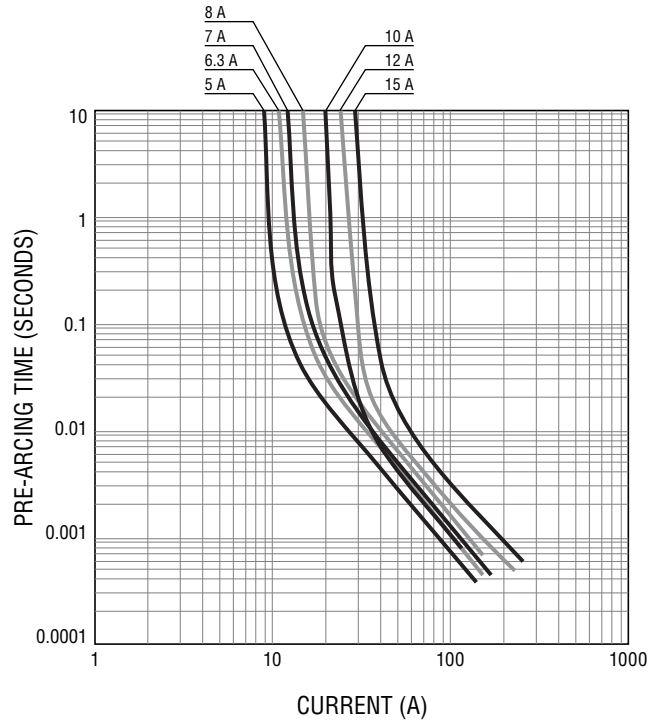


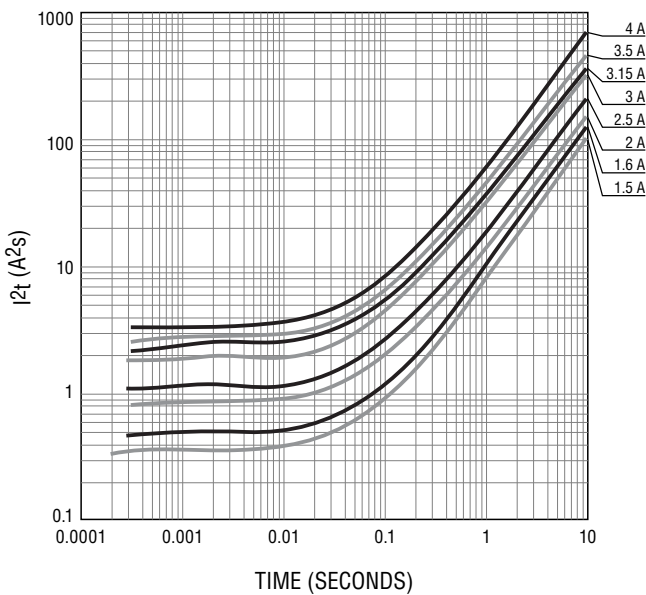
Average Pre-Arcing Time vs. Current Curves (1.5 - 4 A)



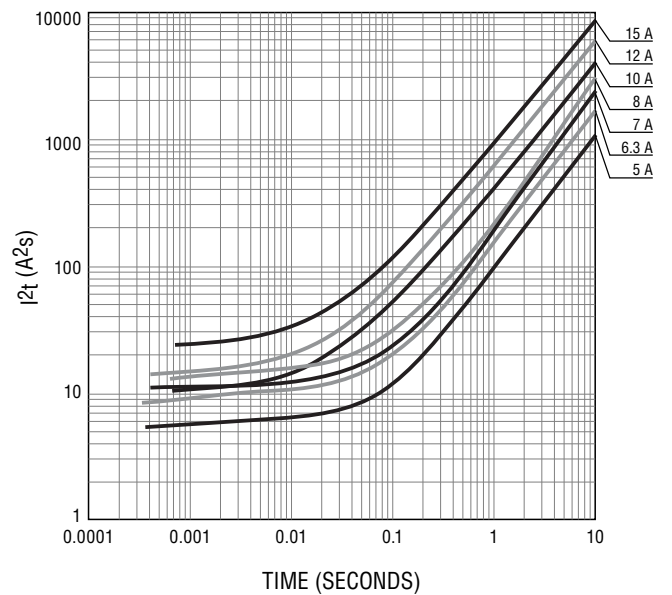
Average Pre-Arcing Time vs. Current Curves (5 - 15 A)



Average I^2t vs. t Curves (1.5 - 4 A)



Average I^2t vs. t Curves (5 - 15 A)

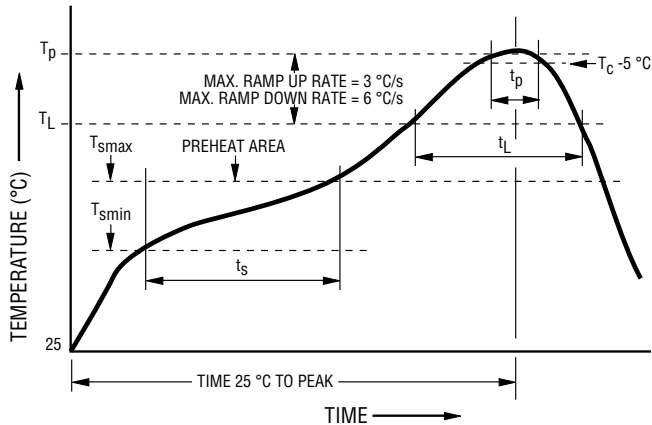


Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

The products described herein and this document are subject to specific legal disclaimers as set forth on the last page of this document, and at www.bourns.com/docs/legal/disclaimer.pdf.

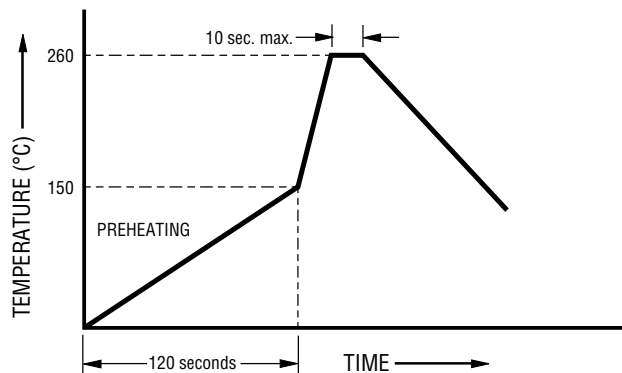
Solder Reflow Recommendations



| Profile Feature | Pb-Free Assembly |
|---|------------------------------------|
| Preheat / Soak: Temperature Min. (T_{smin}) Temperature Max. (T_{smax}) Time (t_s) from (T_{smin} to T_{smax}) | 150 °C 200 °C 60~120 seconds |
| Ramp Up Rate (T_L to T_p) | 3 °C / second max. |
| Liquidous Temperature (T_L) Time (t_L) maintained above T_L | 217 °C 60~150 seconds |
| Peak Package Body Temperature (T_p) | 260 °C |
| Time (t_p)* within 5 °C of the specified classification temperature (T_C) | 30 seconds* |
| Ramp Down Rate (T_p to T_L) | 6 °C / second max. |
| Time 25 °C to Peak Temperature | 8 minutes max. |

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

Solder Wave Recommendations



Reliability Tests

| Test Items | Reference Standard |
|---------------------------------|-------------------------|
| Visual Inspection | MIL-STD-883 Method 2009 |
| High Temperature Storage | MIL-STD-202 Method 108 |
| Low Temperature Storage | IEC 60068-2-1 |
| Temperature Cycling | JESD22 Method JA-104 |
| Biased Humidity | MIL-STD-202 Method 103 |
| High Temperature Operating Life | MIL-STD-202 Method 108 |
| Physical Dimension | JESD22 Method JB-100 |
| Mechanical Vibration | MIL-STD-202 Method 204 |
| Mechanical Shock | MIL-STD-202 Method 213 |
| Resistance to Soldering Heat | MIL-STD-202 Method 210 |
| Salt Spray | MIL-STD-202 Method 101 |
| Solderability | MIL-STD-202 Method 208 |
| Terminal Strength | AEC-Q200-006 |
| Board Flex | AEC-Q200-005 |
| Electrical Characterization | Bourns Specification |



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